

Docket No.: 1999P2628

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : LOTHAR BAUCH ET AL.
Filed : CONCURRENTLY HEREWITH
Title : STACKED VIA WITH SPECIALLY DESIGNED LANDING PAD FOR
INTEGRATED SEMICONDUCTOR STRUCTURES

#4/205
Andum
8/13/02



INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

U.S. Patent 5,591,673 (Chao et al.), dated January 7, 1997;

U.S. Patent 5,894,170 (Ikshikawa), dated April 13, 1999;

German Published Non-Prosecuted Patent Application DE 198 02 161 A1 (inventor will be mentioned later), dated July 22, 1999, method for producing stacked vias;

International Search Report, dated January 22, 2001.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,

A large, stylized handwritten signature in black ink, likely belonging to Laurence A. Greenberg.

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For Applicants

Date: February 25, 2002

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